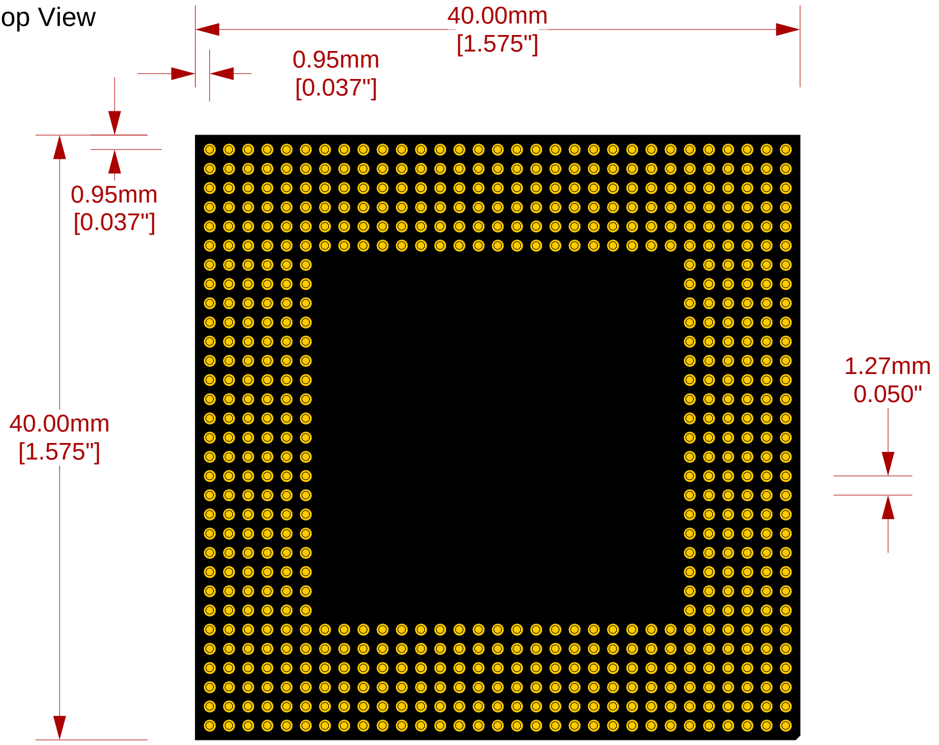
Patent Pending

Top View

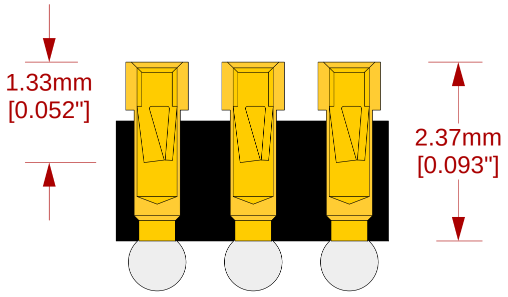


Ordering Information:

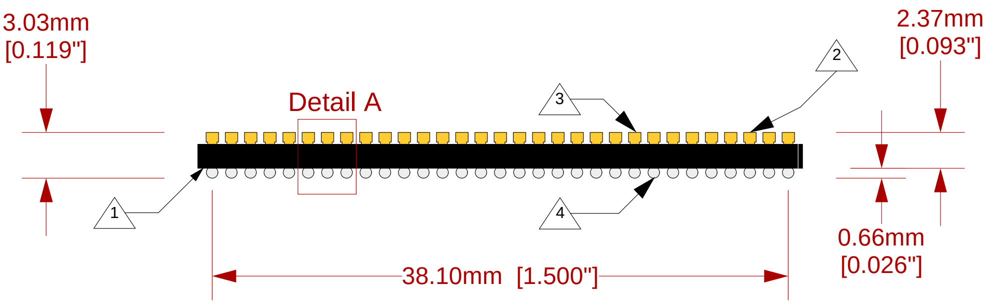
Solder Ball Alloy	Part Number Suffix
Sn63Pb37	-32
Sn96.5Ag3.0Cu0.5	-32F*

*RoHS Compliant

Side View



Detail A



CONTACT DATA
Accepts 0.20mm - 0.33mm Diameter pins
3-finger
37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)
30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)
20/17 gram, extraction force (with 0.254mm0.203mm dia. pin)

1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. (RoHS)

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25μm [10μ"] Au over 1.27μm [50μ"] Ni (min.).

3 Contacts: Beryllium Copper Alloy172, HT; Finish- 0.25μm [10μ"] Au over 1.27μm [50μ"] Ni (min.).

4 Solder Balls:See table Above

Description: Giga-snaP BGA SMT Foot
600 position (1.27mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin asignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.18mm [±0.007"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA600C-B-32(F) Drawing	Status: Released	Scale: 3:1	Rev: A
© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R	Date:2/18/10	
	File: SF-BGA600C-B-32 Dwg	Modified:	